## Statement of Materials, Construction

### 16L OPLGA – TABLE OF MATERIAL DECLARATION

<table>
<thead>
<tr>
<th>No.</th>
<th>Component Name</th>
<th>Material Name</th>
<th>Component Weight (grams)</th>
<th>Weight Analysis (Element / Compound)</th>
<th>CAS Number</th>
<th>Material Mass (Gram)</th>
<th>Material Weight % (of Total Pkg)</th>
<th>Material Weight % (of Component)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Substrate</td>
<td>BT Resin</td>
<td>0.02351</td>
<td>BT Epoxy Proprietary</td>
<td>0.01022</td>
<td>28.69409</td>
<td>43.45</td>
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</tr>
<tr>
<td></td>
<td></td>
<td>Solder Mask</td>
<td></td>
<td>Proprietary</td>
<td>0.00361</td>
<td>10.13043</td>
<td>15.34</td>
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<tr>
<td></td>
<td></td>
<td>Cu</td>
<td>0.00926</td>
<td>7440-50-8</td>
<td>0.00032</td>
<td>0.90474</td>
<td>1.37</td>
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</tr>
<tr>
<td></td>
<td></td>
<td>Au</td>
<td>0.00111</td>
<td>7440-02-0</td>
<td>0.00011</td>
<td>0.29718</td>
<td>0.45</td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>Die</td>
<td>Silicon Chip</td>
<td>0.000290</td>
<td>Si</td>
<td>7440-21-3</td>
<td>0.00029</td>
<td>0.81053</td>
<td>99.5</td>
</tr>
<tr>
<td>3</td>
<td>Die attach material</td>
<td>Conductive Epoxy</td>
<td>0.000270</td>
<td>Epoxy resin Proprietary</td>
<td>0.00004</td>
<td>0.11376</td>
<td>15</td>
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<tr>
<td></td>
<td></td>
<td>Ag</td>
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<td>7440-21-3</td>
<td>0.00022</td>
<td>0.60674</td>
<td>80</td>
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<tr>
<td></td>
<td></td>
<td>Diester</td>
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<td>Proprietary</td>
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<td>0.03792</td>
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<tr>
<td></td>
<td></td>
<td>Functionalized Ester</td>
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<td>Proprietary</td>
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<td>0.00000</td>
<td>0</td>
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<tr>
<td>4</td>
<td>Wire</td>
<td>Gold</td>
<td>0.0015000</td>
<td>Au</td>
<td>7440-57-5</td>
<td>0.00150</td>
<td>4.21306</td>
<td>99.99</td>
</tr>
<tr>
<td>5</td>
<td>Encapsulation</td>
<td>Epoxy Resin</td>
<td>0.01003</td>
<td>Bisphenol A type</td>
<td>25068-38-6</td>
<td>0.00542</td>
<td>15.21404</td>
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<tr>
<td></td>
<td></td>
<td>Epoxy resin</td>
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<td>2451-62-9</td>
<td>0.0160</td>
<td>4.50787</td>
<td>16</td>
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<tr>
<td></td>
<td></td>
<td>Tetra Hydrophthalic Anhydride</td>
<td>85-43-8</td>
<td>0.03009</td>
<td>8.45225</td>
<td>30</td>
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<td></td>
<td></td>
<td>Halogenated Flame Retardants</td>
<td>Proprietary</td>
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<td>0.00000</td>
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<td></td>
<td></td>
<td></td>
<td></td>
<td>Total Package weight</td>
<td>0.03560</td>
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</tbody>
</table>

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

<table>
<thead>
<tr>
<th>Material</th>
<th>Maximum Allowable Limit (ppm)</th>
<th>Maximum Allowable Limit (wt %)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Lead</td>
<td>1000 ppm</td>
<td>0.10%</td>
</tr>
<tr>
<td>Mercury</td>
<td>1000 ppm</td>
<td>0.10%</td>
</tr>
<tr>
<td>Cadmium</td>
<td>100 ppm</td>
<td>0.01%</td>
</tr>
<tr>
<td>Hexavalent Chromium</td>
<td>1000 ppm</td>
<td>0.10%</td>
</tr>
<tr>
<td>Polybrominated Biphenyls (PBB)</td>
<td>1000 ppm</td>
<td>0.10%</td>
</tr>
<tr>
<td>Polybrominated Biphenylethers (PBDE)</td>
<td>1000 ppm</td>
<td>0.10%</td>
</tr>
</tbody>
</table>